



02-04-04

Docket No. 6353/P1/DSM/LOW K/JW

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Re: Inventor(s): Howard Li, L. Luo, I. Iliopoulos and M. Armacost  
Title: INTEGRATED EQUIPMENT SET FOR FORMING A LOW K DIELECTRIC INTERCONNECT ON A SUBSTRATE  
Serial No.: 10/759,801  
Filed: January 16, 2004

Transmitted herewith is:

- ☒ Information Disclosure Statement  
☒ PTO Form 1449 with seventy-six cited references  
☒ Return Postcards

FEE CALCULATION					
Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	N/A	- 20 =	-0-	X \$18.00	\$0.00
Independent Claims	N/A	- 3 =	-0-	X \$84.00	\$0.00
Basic Filing Fee				\$740.00	\$0.00
TOTAL FEES					\$0.00

— The Commissioner is hereby authorized to charge \$0.00 to Deposit Account No. 04-1696.

☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 04-1696. A duplicate copy of this transmittal is enclosed.

☒ Please address all future correspondence to:

PATENT COUNSEL  
APPLIED MATERIALS, INC.  
Legal Affairs Department  
P.O.BOX 450A  
Santa Clara, CA. 95052

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Express Mail Receipt No. EL975550394US

Date of Deposit: 2/3/04

Signature: [Signature]

Respectfully submitted,

[Signature]  
Brian M. Dugan  
Registration No. 41,720  
(914) 332-9081



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PATENTS  
6353/P1/DSM/LOW K/JW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Howard Li, et al.  
Serial No. : 10/759,801  
Filed : January 16, 2004  
For : INTEGRATED EQUIPMENT SET FOR FORMING A LOW K  
DIELECTRIC INTERCONNECT ON A SUBSTRATE

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97,  
applicants wish to call the attention of the Examiner to the  
following references:

U.S. Patent No. 3,156,073, Strasbaugh  
U.S. Patent No. 3,564,776, Aspden  
U.S. Patent No. 3,691,694, Goetz et al.  
U.S. Patent No. 3,603,042, Boettcher  
U.S. Patent No. 3,693,301, Lemaitre  
U.S. Patent No. 5,427,878, Corliss  
U.S. Patent No. 6,051,113, Moslehi  
U.S. Patent No. 6,086,734, Harada  
U.S. Patent No. 6,120,641, Stevens et al.  
U.S. Patent No. 6,143,126, Stevens

U.S. Patent No. 6,166,801, Dishon et al.  
U.S. Patent No. 5,655,110, Krivokapic et al.  
U.S. Patent No. 5,657,254, Sierk et al.  
U.S. Patent No. 5,866,437, Chen et al.  
U.S. Patent No. 5,917,919, Rosenthal  
U.S. Patent No. 5,926,690, Toprac et al.  
U.S. Patent No. 6,161,054 , Rosenthal et al.  
U.S. Patent No. 6,197,604 B1, Miller et al.  
U.S. Patent No. 6,208,751 B1, Almogy  
U.S. Patent No. 6,230,069 B1, Campbell et al.  
U.S. Patent No. 6,245,581 , Bonser et al.  
U.S. Patent No. 6,284,622 B1, Campbell et al.  
U.S. Patent No. 6,368,879 B1, Toprac  
U.S. Patent No. 6,388,253 B1, Su  
U.S. Patent No. 6,405,096 B1, Toprac et al.  
U.S. Patent No. 6,438,440 B1 , Hayashi  
U.S. Patent No. 6,445,969 B1, Kenney et al.  
Foreign Art Reference No. 61164773A2 (Japan)  
Foreign Art Reference No. 61188071A (Japan)  
Foreign Art Reference No. 61244460 (Japan)  
Foreign Art Reference No. 61265262A (Japan)  
Foreign Art Reference No. 63256342A2 (Japan)  
Foreign Art Reference No. 3142929A2 (Japan)  
Foreign Art Reference No. 4217456 (Japan)  
Foreign Art Reference No. 569311A (Japan)

Foreign Art Reference No. 639704A (Japan)

Foreign Art Reference No. WO 98/02910 (PCT)

Foreign Art Reference No. WO 99/49500 (PCT)

Foreign Art Reference No. WO 99/59190 (PCT)

Foreign Art Reference No. WO 99/60614 (PCT)

Foreign Art Reference No. 1 052 060 A2 (Europe)

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Foreign Art Reference No. EP 0 932 194 A1 (EPO)

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IBM Technical Disclosure Bulletin: "Dry Point  
Detection System," Dec. 1976, pp. 2507-2509

IBM Technical Disclosure Bulletin: "Making Tunnel  
Barrier Layers by Plasma Deposition," Aug. 1979, p. 1194

IBM Technical Disclosure Bulletin: "Apparatus for  
Locating Particles on a Blank Wafer in a Scanning Electron  
Microscope", May 1984, pp. 6609-6610

IBM Technical Disclosure Bulletin: "Auto-Defect  
Detection/Visual Defect Review Inspection System," Feb. 1989, pp.  
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During and After Resist Strip," May 1989, pp. 295-297

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The Novascan 210, "Integrated On-Line Thickness Monitoring System for CMP Applications", downloaded from <http://www.nova.co.il.scan.htm> on 9/10/96

J. Bruchez et al., "Linking European Suppliers with Global Users," Semiconductor International, March 1998

J. Baliga, "MES and CIM: At the Center of Productivity," Semiconductor International, July 1998

A. Braun, "Inspection, Measurement & Test," Semiconductor International, August 1998

Applied Materials Press Release Archive 1998 "Applied Materials Unveils its Total Solution to Patterned Wafer Defect Detection," downloaded from <http://www.appliedmaterials.com/newsroom/pr-00110.html> on 3/12/02

Applied Materials Press Release Archive 1998 "Applied Materials Announced First Process Sequence Integration Product: The Copper Interconnect ESS," downloaded from <http://www.appliedmaterials.com/newsroom/pr-00169.html> on 3/12/02

J. Fraser, "Treating Software Strategically: Beyond Traditional MES," Semiconductor International, January 1999

J. Bruchez et al., "European Suppliers Focusing on Tool Productivity," Semiconductor International, April 1999

J. Baliga, "Advanced Process Control: Soon to be A Must," Semiconductor International, July 1999

J. Baliga, "How Advanced Are We?," Semiconductor International, July 1999

A. Braun, "Metrology Hits the Road to Integration," Semiconductor International, April 2000

T. Zavecz et al., "Life Beyond Mix-and-Match: Controlling Sub-0.18 um Overlay Errors", Semiconductor International, July 2000

F. Poag et al., "Implementing on-line ADC and an Automated Yield Information Management System," MICROmagazine.com, July, 2000

A. Toprac et al., "Run-to-Run Control of Shallow Trench Isolation Etch," AEC/APC 2000

N. Patel, "Mix Issues in Process Control," Sematech AEC/APC Symposium XII, September 25, 2000

J. Holden et al., "Characterizing a CVD-Integrated Metrology System," Semiconductor International, October 2000

A. Braun, "IMA Continues Important APC Standards Work," Semiconductor International, December 2000

L. Peters, "Yield Management Motorola and Infineon Improve APC Strategy," Semiconductor International, February 2001

"Applied Materials Leads the Industry with Process  
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Validates Groundbreaking Concept," San Francisco (Business Wire)  
July 16, 2001

Nanometrics' NanoSpec 9000 Series Integrated Metrology  
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<http://www.nanometrics.com/ProductsIntegrated.htm> on 9/17/01

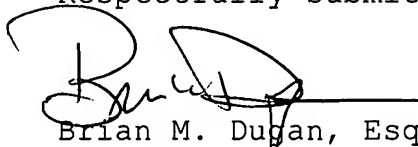
"Applied Materials Launches Industry's First In-Line  
Metrology SEM System with 3D Imaging," Jan. 10, 2000, downloaded  
from [http://www.semiseek.com/News/press\\_release55.html](http://www.semiseek.com/News/press_release55.html)

Solid State Technology; Claasen-Vujcic et al;  
"Analysis of a 200/300mm Vertical Furnace with Integrated  
Technology"; April 2001; pps. s6, s8, s12

Pursuant to 37 CFR §1.98 (d) Applicants have not  
enclosed copies of the cited references as they were previously  
cited in a prior application (U.S. Patent Application Serial No.  
10/459,194, filed June 11, 2003).


Consideration of the foregoing in relation to this  
patent application is respectfully requested.

Respectfully Submitted,

A handwritten signature in black ink, appearing to read "Brian M. Dugan", with a horizontal line extending to the right.

Brian M. Dugan, Esq.  
Registration No. 41,720  
Dugan & Dugan, PC  
Attorneys for Applicants  
(914)332-9081

Dated: 2/3/04  
Tarrytown, New York

U.S. Department of Commerce, Patent and Trademark Office  					Docket No.: 6353/P1/DSM/LOW K/JW		Serial No.: 10/759,801	
LIST OF RELEVANT ART CITED BY APPLICANT (Use several sheets if necessary)					Applicant(s): Howard Li, et al.			
					Filing Date: January 16, 2004		Group: Unknown	
U.S. Patent Documents								
*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	3,156,073	11/10/64	Strasbaugh				
	AB	3,564,776	02/23/71	Aspden				
	AC	3,691,694	09/19/72	Goetz et al.				
	AD	3,603,042	09/07/71	Boettcher				
	AE	3,693,301	09/26/72	Lemaitre				
	AF	5,427,878	06/27/95	Corliss				
	AG	6,051,113	04/18/00	Moslehi				
	AH	6,086,734	07/11/00	Harada				
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	AJ	6,143,126	11/07/00	Stevens				
	AK	6,166,801	12/26/00	Dishon et al.				
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		Document Number	Date	Country	Class	Subclass	Yes	No
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	AM	61188071A	08/21/86	Japan			Abstract Only	
	AN	61244460	10/30/86	Japan			Abstract Only	
	AO	61265262A	11/25/86	Japan			Abstract Only	
	AP	63256342A2	10/24/88	Japan			Abstract Only	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
	AR	IBM Technical Disclosure Bulletin: "Dry Point Detection System," Dec. 1976, pp. 2507-2509						
	AS	IBM Technical Disclosure Bulletin: "Making Tunnel Barrier Layers by Plasma Deposition," Aug. 1979, p. 1194						
	AT	IBM Technical Disclosure Bulletin: "Apparatus for Locating Particles on a Blank Wafer in a Scanning Electron Microscope", May 1984, pp. 6609-6610						
Examiner			Date Considered					
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.								

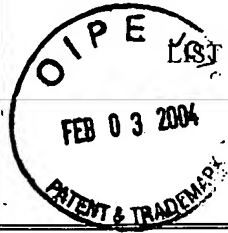
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Group:

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## U.S. Patent Documents

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	AA	5,655,110	08/05/97	Krivokapic et al.			
	AB	5,657,254	08/12/97	Sierk et al.			
	AC	5,866,437	02/02/99	Chen et al.			
	AD	5,917,919	06/29/99	Rosenthal			
	AE	5,926,690	07/20/99	Toprac et al.			
	AF	6,161,054	12/12/00	Rosenthal et al.			
	AG	6,197,604 B1	03/06/01	Miller et al.			
	AH	6,208,751 B1	03/27/01	Almog			
	AI	6,230,069 B1	05/08/01	Campbell et al.			
	AJ	6,245,581 B1	06/12/01	Bonser et al.			
	AK	6,284,622 B1	09/04/01	Campbell et al.			

## Foreign Patent Documents

## Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
	AL	3142929A2	06/18/91	Japan			Abstract Only	
	AM	4217456	08/07/92	Japan			Abstract Only	
	AN	569311A	03/23/93	Japan			Abstract Only	
	AO	639704A	02/15/94	Japan			Abstract Only	
	AP	WO 98/02910	01/22/98	PCT				

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	AR	IBM Technical Disclosure Bulletin: "Auto-Defect Detection/Visual Defect Review Inspection System," Feb. 1989, pp. 306-307
	AS	IBM Technical Disclosure Bulletin: "Dual Microscope Semiconductor Wafer Inspection Machine," March 1989, pp. 474-479
	AT	IBM Technical Disclosure Bulletin: "Integrated Semiconductor Processing Facilitation by Mobile Ion Gettering During and After Resist Strip," May 1989, pp. 295-297

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	AB	6,388,253 B1	05/14/02	Su			
	AC	6,405,096 B1	06/11/02	Toprac et al.			
	AD	6,438,440 B1	08/20/02	Hayashi			
	AE	6,445,969 B1	09/03/02	Kenney et al.			
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	AM	WO 99/59190	11/18/99	PCT				
	AN	WO 99/60614	11/25/99	PCT				
	AO	1 052 060 A2	11/15/00	Europe				
	AP	WO 00/57127	09/28/00	PCT				

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	AR	IBM Technical Disclosure Bulletin: "Automated Multiple Angle of Incidence Ellipsometer System," Feb. 1990, pp. 417-424
	AS	IBM Technical Disclosure Bulletin: "Multiprocessor and Multitasking Architecture for Tool Control of the Advanced via Inspection Tools," May 1992, pp. 190-191
	AT	The Novascan 210, "Integrated On-Line Thickness Monitoring System for CMP Applications", downloaded from <a href="http://www.nova.co.il.scan.htm">http://www.nova.co.il.scan.htm</a> on 9/10/96

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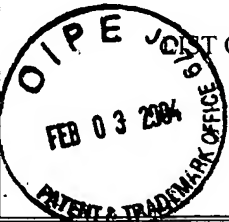
		Document Number	Date	Country	Class	Subclass	Yes	No
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	AM	WO 00/79355 A1	12/28/00					
	AN	WO 02/04886 A1	01/17/02					
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	AP							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	AR	J. Bruchez et al., "Linking European Suppliers with Global Users," Semiconductor International, March 1998
	AS	J. Baliga, "MES and CIM: At the Center of Productivity," Semiconductor International, July 1998
	AT	A. Braun, "Inspection, Measurement & Test," Semiconductor International, August 1998

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AR	Applied Materials Press Release Archive 1998 "Applied Materials Unveils its Total Solution to Patterned Wafer Defect Detection," downloaded from <a href="http://www.appliedmaterials.com/newsroom/pr-00110.html">http://www.appliedmaterials.com/newsroom/pr-00110.html</a> on 3/12/02	
AS	Applied Materials Press Release Archive 1998 "Applied Materials Announced First Process Sequence Integration Product: The Copper Interconnect ESS," downloaded from <a href="http://www.appliedmaterials.com/newsroom/pr-00169.html">http://www.appliedmaterials.com/newsroom/pr-00169.html</a> on 3/12/02	
AT	J. Fraser, "Treating Software Strategically: Beyond Traditional MES," Semiconductor International, January 1999	

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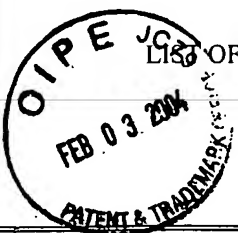
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AS	T. Zavec et al., "Life Beyond Mix-and-Match: Controlling Sub-0.18 um Overlay Errors", Semiconductor International, July 2000
AT	F. Poag et al., "Implementing on-line ADC and an Automated Yield Information Management System," MICROmagazine.com, July, 2000

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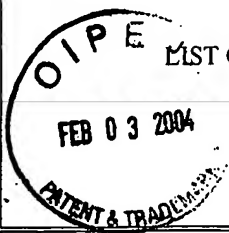
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AS	N. Patel, "Mix Issues in Process Control," Sematech AEC/APC Symposium XII, September 25, 2000	
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Foreign Patent Documents							Translation	
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AS	L. Peters, "Yield Management Motorola and Infineon Improve APC Strategy," Semiconductor International, February 2001	
AT	"Applied Materials Leads the Industry with Process Module Approach for Nanometer Generation Chipmaking Data Validates Groundbreaking Concept," San Francisco (Business Wire) July 16, 2001	
Examiner _____ Date Considered _____		

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

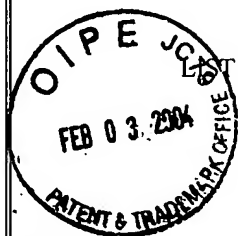
U.S. Department of Commerce, Patent and Trademark Office

Docket No.:

6353/P1/DSM/LOW K/JW

Serial No.:

10/759,801



LIST OF RELEVANT ART CITED BY APPLICANT

(Use several sheets if necessary)

Applicant(s):

Howard Li, et al.

Filing Date:

January 16, 2004

Group:

Unknown

## U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

## Foreign Patent Documents

## Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
	AL							
	AM							
	AN							
	AO							
	AP							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AR	Nanometrics' NanoSpec 9000 Series Integrated Metrology Systems, downloaded from <a href="http://www.nanometrics.com/ProductsIntegrated.htm">http://www.nanometrics.com/ProductsIntegrated.htm</a> on 9/17/01
AS	"Applied Materials Launches Industry's First In-Line Metrology SEM System with 3D Imaging," Jan 10, 2000, downloaded from <a href="http://www.semiseek.com/News/press_release55.html">http://www.semiseek.com/News/press_release55.html</a>
AT	Solid State Technology; Claasen-Vujcic et al; "Analysis of a 200/300mm Vertical Furnace with Integrated Technology"; April 2001; pps. s6, s8, s12

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